

## SLOVENSKI STANDARD SIST EN 150001:2002

01-september-2002

Blank detail specification: General purpose semiconductor diodes

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Vordruck für Bauartspezifikation: Allzweck-Halbleiterdioden

Spécification particulière cadre: Diodes à semiconducteur d'usage général

Ta slovenski standard je istoveten z: EN 150001:199

<u>SIST EN 150001:2002</u>

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ICS:

31.080.10 Diode Diodes

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## EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

EN 150001

December 1991

| UDC:

Descriptors: Quality, electronic components, diodes

English version

## Blank Detail Specification: General purpose semiconductor diodes

Spécification Particulière Cadre: Diodes à semiconducteur d'usage général Vordruck für Bauartspezifikation: Allzweck-Halbleiterdioden

### iTeh STANDARD PREVIEW

This European Standard was approved by the CENELEC Electronic Components Committee (CECC) on 25 November 1991. The text of this standard consists of the text of CECC 50001 Issue 2 1980 of the corresponding CECC Specification. CENELEC members are bound to comply with CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the General Secretariat of the CECC or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CECC General Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom. The membership of the CECC is identical, with the exception of the national electrotechnical committees of Greece, Iceland and Luxembourg.

### CECC

European Committee for Electrotechnical Standardization Comité Européen de Normalisation Electrotechnique Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

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**CECC 50 001** 

European Committee for Electrotechnical Standardization (CENELEC)
Cenelec Electronic Components Committee



English version

Harmonized System of Quality Assessment for Electronic Components



**BLANK DETAIL SPECIFICATION:** 

GENERAL PURPOSE SEMICONDUCTOR DIODES

# i<u>Teh STANDA</u>RD PREVIEW (standards.iteh.ai)

Système Harmonisé d'Assurance de la Qualité

des Composants Electroniques

https://standards.tich.ai/catalog/standards/sist/c1bd6257-dl/2e-4824-a1a9-

SPECIFICATION PARTICULIERE CADRE:

DIODES A SEMICONDUCTEURS
D'USAGE GENERAL

Harmonisiertes Gütebestätigungssystem für Bauelemente der Elektronik

VORDRUCK FUR BAUARTSPEZIFIKATION:

ALLZWECK-HALBLEITERDIODEN



**CECC 50001** 

1980

#### Foreword

The CENELEC Electronic Components Committee (CECC) is composed of those member countries of the European Committee for Electrotechnical Standardization (CENELEC) who wish to take part in a harmonized System for electronic component of assessed quality.

The object of the System is to facilitate international trade by the harmonization of the specifications and quality assessment procedures for electronic components, and by the grant of an internationally recognised Mark or Certificate, of Conformity. The components produced under the System are thereby accepted by all member countries without further testing.

This document has been formally approved by the CECC, and has been prepared for those member countries taking part in the System who wish to issue national harmonized specifications for GENERAL PURPOSE SEMICONDUCTOR DIODES. It should be read in conjunction with document CECC 00100: Basic Rules (1974).

#### Preface

This blank detail specification was prepared by CECC Working Group 5: "Semiconductor diodes and transistors". It is one of a series of blank detail specifications for discreate semiconductor devices, relating to the generic specification CECC 50000.

- 1) the addition of a Sub-Group A2a to check non-operative devices, which will become obligatory in all existing detail specifications by 1st January 1981. Until that date, implementation is optional (see below)
- 2) the addition of requirements for controlled-avalanche diodes DR RVIII
- 3) the addition of clauses 6, 7 and 9
- 4) the change in lay-out

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#### Implementation

All qualifications according to Issue 1 remain technically valid as well as all detail specification prepared in accordance with Issue 1 even if they are not completely 824-a1a9-in line with items 2), 3) and 4) above. Before 1st January 1981, however, all detail specifications shall be amended — and their issue number raised by one by any suitable means, to conform with item 1).

Issue 1 will be withdrawn on 1st January 1961

#### Lay-out

The lay-out of this blank detail specification is amended from that of Issue 1 and will be adopted for all other blank detail specifications. In the meantime this lay-out should be followed, as far as possible, for all detail specifications in the 50000 series. Existing detail specifications need not be changed.

#### Voting

The text of this revised blank detail specification was circulated to the CECC for voting in the documents listed below, and was ratified by the CECC Management Committee for printing as a CECC specification.

Document	Voting Date		Report	on the Voting	Circulation Date			
CECC (Secretariat)	691 July	<b>197</b> 8	CECC	(Secretariat)	<b>753</b>	September	1978	
CECC (Secretariat)	705 August	1978	3CECC	(Secretariat)	765 +	AJune	1979	
CECC (Secretariat)	767 March	1979	CECC	(Secretariat)	816	August	1979	
CECC (Secretariat)	768 March	1979	CECC	(Secretariat)	817	August	1979	
CECC (Secretariat)	771April	1979	CECC	(Secretariat)	818	August	1979	
CECC (Secretariat)	855 October	1979	CECC	(Secretariat)	909	February	1980	

TEXTS BETWEEN SQUARE BRACKETS GIVE GUIDELINES ON HOW TO FILL IN THE BLANK DETAIL SPECIFICATION

#### GENERAL PURPOSE SEMICONDUCTOR DIODES

[Name (	address) of responsible CNH (1	)  Pε	age	CECC 50001-X	XX		2	-	
	sibly of body from which specification is	of		[CECC detail sp plus issue num and/or date]		numb	er d		
Quality in accordance with:			National number of detail specification.  [This box may not be used if National number includes CECC number]						
1 Mecl	hanical description (7	) <u>D</u> e	etail	specification for	<u>r</u> :			<b>⑤</b>	
refere — fro	r outline references (code A) or base and cas ences (codes $\mathrm{B}+\mathrm{C}$ ) m IEC 191-2: tional [if desired]	ap Oi	prop	number (s) of re oriate structura ing information: ent	lly similar d	levice	s]	f	
		2	Sho	ort descript	ion			6	
	OUTLINE DRAWING AND CONNECTIONS	1		onductor materi sulation: metal/		c/			
clause 9	(Terminal connected to case, if any) transferred to, or given with more details ir of this document] standards. steel terms and figures/colour code	) P	R	ation: Sign Swit Cont			(Sig) (Sw) (C-A)		
[see 2.5.6 of CECC 50000 and/or clause 6 of this document]  SIST EN 150001-2 02 Por document]  1a9a28e20afc/sist-en-150001			Power: ambient-rated (Tamb)						
Polarity indication if special method is used			[Some important quick reference data: voltage, power, may be added]						
		3	Lev	vel (s) of qua	ality asse	ssm	ent	8	
				n from Appendi	x IIA of CE	CC 50	000		
4 Limi	iting values (Absolute maximum ra	ting	sys	tem)				9	
	pply over the operating temperature range uted in the detail specification	unless	s oth	erwise stated. Y	K denotes th	at a v	alue sh	nall	
Clause	[Repeat only clause numbers used, with tex	ct. Ad	lditio	nal values, if		V	alue		
CECC any, shall be given at the appropriate place without clause numb (s). Curves should preferably be given in clause 9 of this documents.]				Symbol	min	max	Unit		
4.1	Operating ambient or case temperatures				Tamb/case		X		
4.2 Storage temperatures			Tstg	X	X				
4.3   Reverse voltage, with temperature derating curve if necessary (See 9):			$ _{ m V_R}$		X				
4.3.1	— continuous (direct) reverse voltage				$V_{RM}$		X		
4.3.2	3.2 — peak reverse voltage (if different) under specified pulse conditions								
4.4 Forward current, where appropriate under specified mounting conditions:			$I_{F}(T)$ $I_{FRM}$		X X				
4.4.1									
			_	l, <u>only for Sw,</u>	$I_{FSM}$		X		
L	<u> </u>					J	ــــــــــــــــــــــــــــــــــــــ	ــــــــــــــــــــــــــــــــــــــ	

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4.5	For CA and, where appropriate, for Sig and Sw, power dissipation					
	(special requirements for ventilation/mounting should be specified)					
4.5.1	— either: max. power dissipation versus temperature (see 9)	Ptot (T)		X		
4.5.2	— or: max. virtual (equivalent) junction temperature and absolute	$ T_{ m vt} $		X		
	limit of power dissipation	$ P_{tot} $		∫ X		
4.5.3	plus, <u>for C-A only</u> : peak repetitive and/or non repetitive (surge)	$P_{RRM/RSM}$		37		
	reverse energy	$W_{RRM/RSM}$		X		
_	and/or power (with any qualification such as time, frequency)					
See the relevant Qualified Products List for availability of components made to this specification						

# **5 Electrical characteristics** See clause 8 of this document for inspection requirements (Groups A and C)

[In the following table, characteristics marked X in the "value" columns shall be inserted in the detail specifications; characteristics marked + in the "measured" column are measured in Group A or Sub-Group C2.

Signs between brackets correspond to characteristics given as "Where appropriate" or as alternatives:

- Those characteristics marked "where appropriate" in this clause <u>and</u> in the inspection section shall either be omitted or, if specified, shall then be measured
- For equivalent characteristics given as alternatives, the choice should preferably be left open to allow the use of the same detail specification by different manufacturers or countries.

Repeat only clause numbers used, with text. Additional characteristics, if any, shall be given at the appropriate place without clause number (s).

When several devices are included in the same detail specification, the relevant values should be given on successive lines, where possible avoiding repeating identical value.]

Clause	ured	Characteristics and conditions, at Tombor 2002	004 1 0	V	alue	
CECC 50001	Measu	htf====sta25i3Ciunlessiotherwise.statedsist/c1bd6257-db2e-4 1a9a28e20afc/sist-en-150001-2002	Symbol	min	max	Unit
5.1	+	Reverse current at max continuous reverse voltage $V_R$ max	$I_{R1}$		X	
5.2	+	Reverse current at specified continuous reverse voltage $V_{\rm R2}$ , (preferably $V_{\rm R}$ max) and at a high temperature (4.3.3 of CECC 50000)	$ m I_{R2}$		X	
5.3	+	Forward voltage at high forward current $I_{F1}$	$V_{F1}$		X	
5.4	(+)	(d.c. or pulse as specified) Where appropriate, forward voltage at low forward current $I_{\rm F2}$ (d.c. or pulse as specified)	$ m V_{F2}$	(X)		
5.5	+	Capacitance at specified low $V_R$ , $f = 1 MHz$ (preferred)	$\mathbf{C}_{tot}$		X	
5.6	+	Sw only: Reverse recovery time or recovered charge under specified conditions	$ m t_{rr}/Q_{s}$		X	
5.7	(+)	Sw and C-A only: Where appropriate, forward recovery time under specified conditions	$\mathbf{t_{fr}}$		(X)	
5.8	(+)	For detector applications only: detector voltage efficiency under specified conditions	η	(X)		
5.9		When virtual junction temperature is quoted as a limiting value, thermal resistance junction to ambient or case, shall be given only for information	$egin{array}{l} R_{th(j-amb)} \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$		x	
5.10	+	${\hbox{${C\hbox{-}A$ only:}}}$ Avalanche breakdown voltage at specified reverse current $I_R$ (pulse as specified)	V <sub>(BR)</sub>	X	X	

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#### 6 Marking

[Any particular information other than given in box ⑦ on page 1 and/or 2.5.6 of CECC 50000 shall be specified here.]

#### 7 Ordering information

The following minimum information is necessary to order a specific device, unless otherwise specified:

- precise type number
- CECC reference of detail specification with issue number and/or date when relevant
- level of quality assessment as defined in Appendix II A of CECC 50000, and, if required, screening sequence as defined in Appendix VI of CECC 50000
- any other particulars.

[example: 1N000 to CECC 50001-000 Issue 2, level F]

#### 8 Test conditions and inspection requirements

These are given in the following tables, where the values and exact test conditions to be used should be specified as required for a given type, and as required by the relevant test in CECC 50000.

[When several devices are included in the same detail specification, the relevant conditions and/or values should be given on successive lines, where possible avoiding repetition of identical conditions and/or values.

The choice between alternative tests should preferably be left open, unless very sound technical reasons forbid this. Although such tests are not strictly equivalent, they are meant to achieve the same results which are to assess the correct manufacture of a device. Alternatives were provided to take into account different equipments or methods of measurement used in various countries.]

In this section, references to clause numbers are made with respect to CECC 50000 unless otherwise stated.

#### SIS Group A TI-Lot by lot

All tests are non destructive (3.5.6)/catalog/standards/sist/c1bd6257-db2e-4824-a1a9-

Examination or test	Conditions at Tame or Face = 25 °C2		Inspection				
(Ref. 4.3.4/)	unless otherwise stated		ts (see	Assessment			
		min	max	Unit			
Sub-Group A1					Ge.		
Visual inspection	4.2.1		İ		2 D PS		
Sub-Group A2a	[State relevant limits -→]				FE Palit		
Non operative devices					K REFE		
	or $I_R > 100 I_{R1}$ max)	<u> </u>					
Sub-Group A2b							
	$V_R = \max \text{ continuous}$		X				
1	$I_{F1} = high (d.c. or pulse^a as specified)$		X		E P E		
C-A only		ļ			ENTS S OF icable page		
$V_{(ER)}$ (D-009)	$I_R$ = specified (pulse <sup>a</sup> as specified)	X	X	•	ES Car		
Sub-Group A3					REMENT LUES OF applicabl ) on page		
Sw only							
$t_{rr}$ (D-004)	$I_F$ , $i_{rr}$ and $(V_R, R_L)$ or $I_{RM}$ = specified		X		2 5 X		
or			or		ING REQU CODUCE, V (according t ated in box		
$Q_s$ (D-003)	$I_F$ , reverse circuit conditions = specified		X				
Sw/C-A only:		İ	İ		SC C C C C C C C C C C C C C C C C C C		
Where appropriate:					口语:花		
$t_{\rm fr}$ (D-005)	$V_R$ , $I_F$ = specified		X		REP 0000 ent s		
	recovery voltage — see D-005				X R SO SO ME		
Sub-Group A4					S C C S		
Available if required					FOR SAMI TO, OR REI CECC 5000 assessment		
NOTE: The second second		1	1 70	1 177			

NOTE The relevant min and max limits of Group A are referred to later on, in Groups B and C, as LSL and USL (lower/upper specification limit)

<sup>a</sup> preferred pulse conditions:  $t_p = 300 \mu s \delta \le 2 \%$